

Soldering Instructions

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This document shows wave soldering and reflow soldering process that devices are Pb free plated. The well quality of solder joint will be available that following detail information as below:

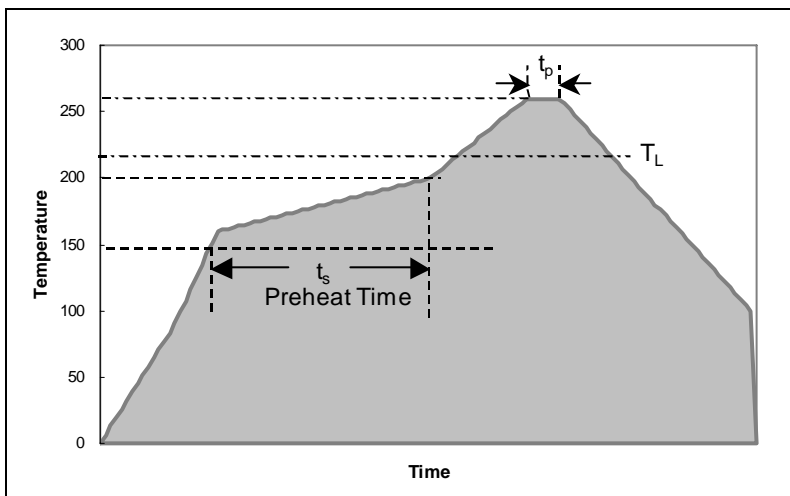
Wave Soldering Process for Through-Hole Mounted Devices

Solder bath: $260 \pm 5^\circ\text{C}$

Dwell time: $10 +2/-0$ sec.

NOTE: The material and process are following JESD22-B106C.

Reflow Soldering Process for Surface Mounted Devices



| Profile Feature | Lead Free Assembly |
|------------------------------|---------------------------|
| Ramp-Up Rate | 2-3°C/S |
| Preheat Temperature | 150-200°C |
| Preheat Time (t_s) | 60-120S |
| Liquid Temperature (T_L) | 217°C |
| Time maintained above T_L | 60-90S |
| Peak Temperature (T_p) | $260 \pm 5^\circ\text{C}$ |
| Peak Time (t_p) | Max 10S |
| Ramp-Down Rate | 3-5°C/S |

NOTE: The material and process are following IPC/JEDEC J-STD-020D.

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